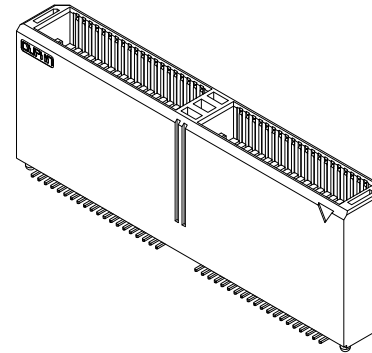
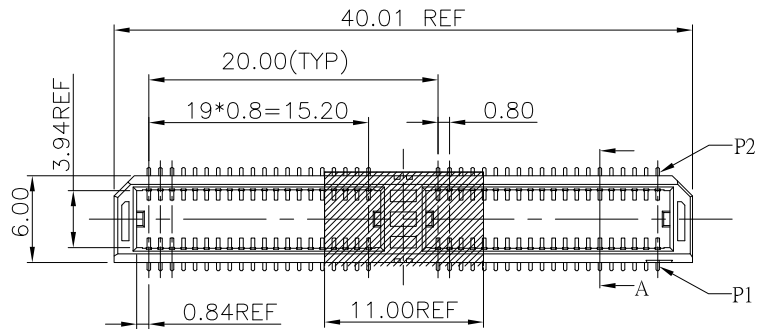


REV.	SPECIFICATION	ECN NO.	APPD.
R3		ECN220902	



**Material and Plating:**

Housing: LCP, UL94V-0 , Black.

Signal Contacts : Brass

Gold Plated on Contact Area and 80u" Min Tin Plated on Solder Tail over nickel 50u" Min .

**Electrical Characteristics:**

Current Rating: 2A.

Voltage Rating: 125V AC .

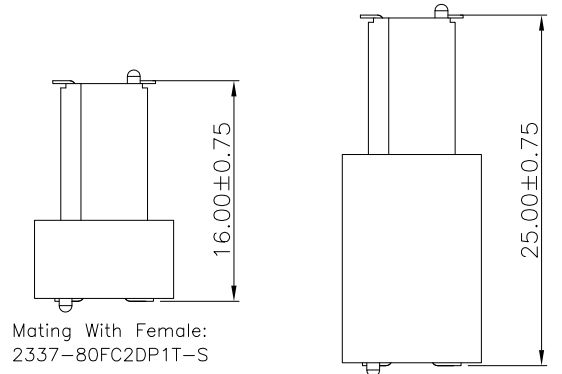
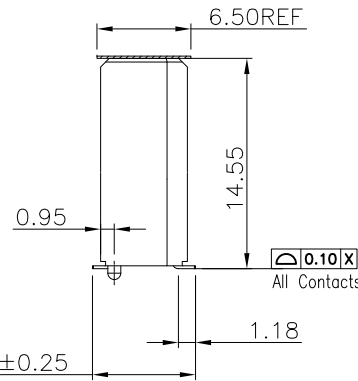
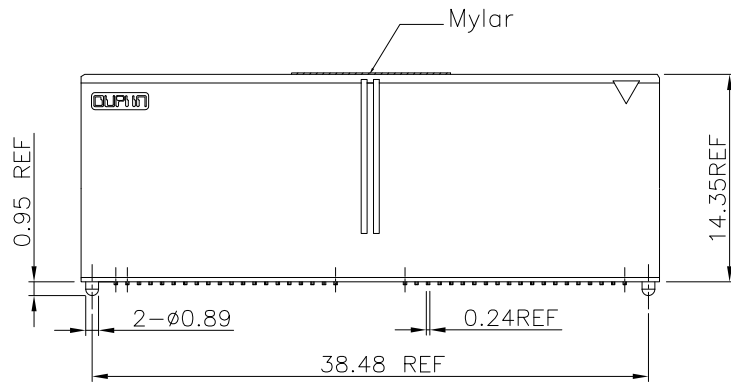
Dielectric Withstanding Voltage: 525V AC For 1 minute.

Insulator Resistance: 5000MΩ min at DC 500V.

Contact Resistance: Signal Pin: 45mΩ max .

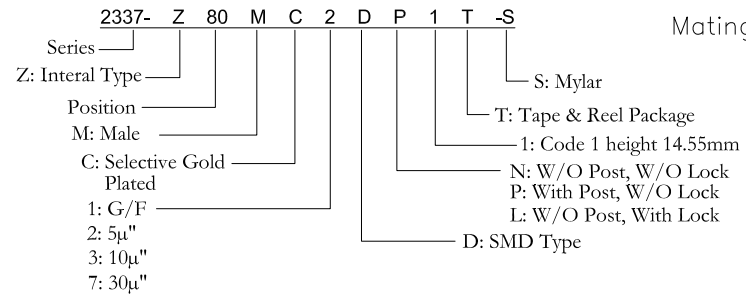
Operating Temperature: -55°C ~ +125°C .

**\*RoHS Compliant**



Mating With Female:  
2337-80FC2DP1T-S

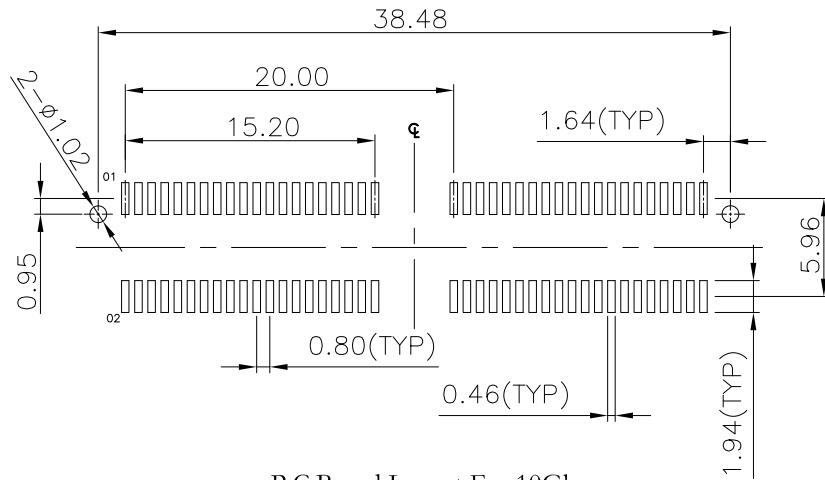
Mating With Female:  
2337-80FC2DP2T-S



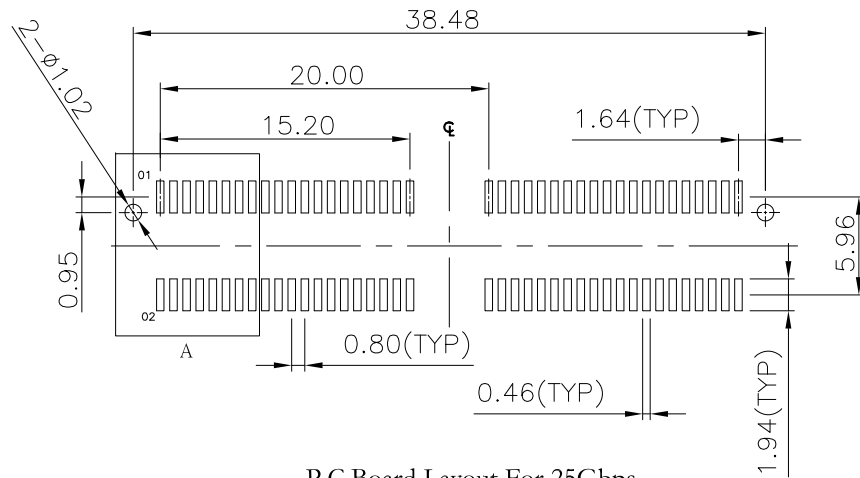
Mating Height

Tolerances	Dwg No.	2337-D0000-002	Title:		 <b>OUPIIN ELECTRONIC(KUNSHAN) CO., LTD.</b> P/N: 2337-Z80MC2DP1T-S SHEET 1/2 Ver.No. R3
x. = ±0.50	Projection			2337 Series	
.x = ±0.25	Unit mm	Scale	1:1	High Speed Board to Board	
.xx = ±0.15	Drawn By	GYJ 06/29'22		Pitch 0.8mm (Plug)	

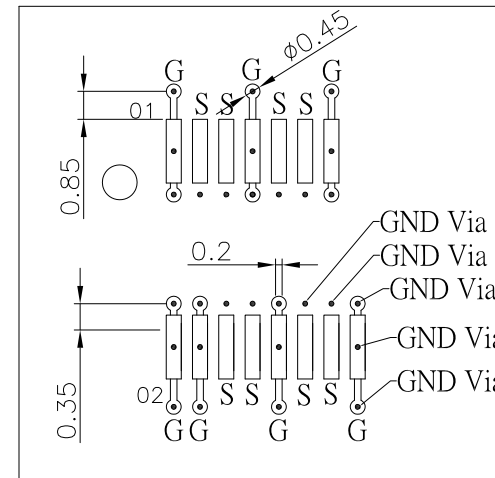
REV.	SPECIFICATION	ECN NO.	APPD.
R3		ECN220902	



P.C.Board Layout For 10Gbps  
(Tolerance:±0.05)



P.C.Board Layout For 25Gbps  
(Tolerance:±0.05)



Detail A  
Scale 2:1

Tolerances	Dwg No.	2337-D0000-002	Title:		 <b>OUPIN ELECTRONIC(KUNSHAN) CO., LTD.</b> P/N: 2337-Z80MC2DP1T-S
x. = ±0.50	Projection		2337 Series		
.x = ±0.25	Unit	mm	Scale	1:1	SHEET
.xx = ±0.15	Drawn By	GYJ 06/29'22	High Speed Board to Board		2/2
			Pitch 0.8mm (Plug)		Ver.No.
					R3